ABSTRACT

WAFER ROTARY HOLDING APPARATUS AND WAFER SURFACE TREATMENT APPARATUS WITH WASTE LIQUID RECOVERY

Provided is a wafer rotary holding apparatus by which a reduced pressure is created on an upper surface of a rotary disk by a simple and easy-to-make mechanism with no need of any of a vacuum source apparatus, a compressed air supply apparatus, a compressed gas supply apparatus and other apparatuses in use; a wafer can be held while rotating with no contact to a rear surface thereof; a degree of pressure reduction can be adjusted with ease and even a thin wafer (of 0.1 mm or less in thickness) can be held while rotating with no deformation; and the wafer with a bowing can be held while rotating with no correction of the bowing. A wafer rotary holding apparatus includes: a rotary disk on which a fluid flow path is formed; a through hole formed in a central section of the rotary disk; and a plurality of wafer rests provided on an upper surface of the rotary disk.

(Fig. 1)